



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

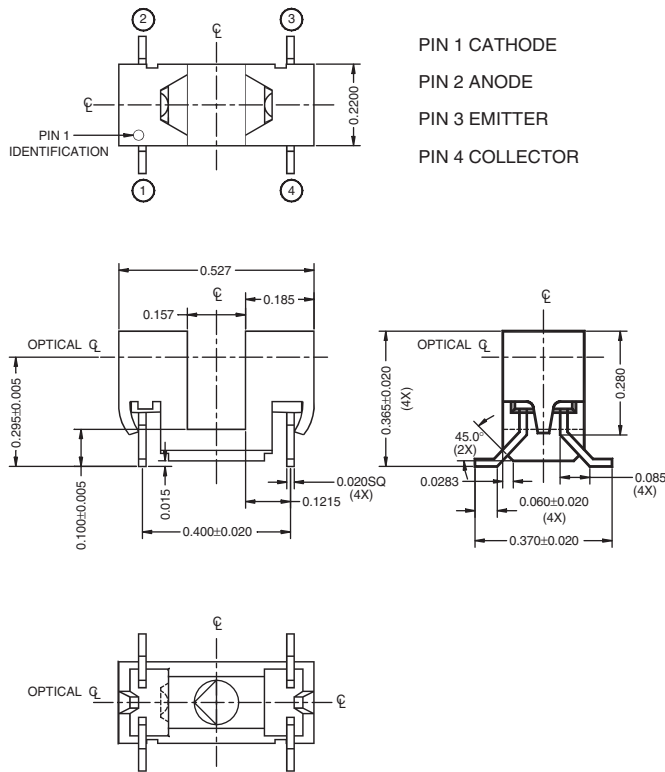
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

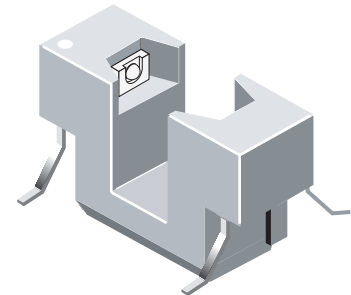
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



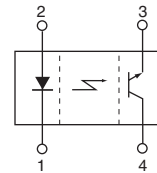
PACKAGE DIMENSIONS



PIN 1 CATHODE
PIN 2 ANODE
PIN 3 EMITTER
PIN 4 COLLECTOR



SCHEMATIC



NOTES:

1. Dimensions for all drawings are in inches.
2. Tolerance of $\pm .010$ on all non-nominal dimensions unless otherwise specified.
3. All leads are coplanar within .006".
4. Housing material is electrically conductive.

DESCRIPTION

The QCK3/QCK4 is a slotted optical switch designed for surface mount applications where extreme temperatures are experienced during solder reflow. The switch consists of a GaAs LED and a silicon photodarlington facing each other across a .157" (4.0 mm) gap. The leads are formed to sit flush on a PCB during solder reflow.

FEATURES

- Unique single piece housing designed to reduce cost.
- High temperature housing material to withstand extreme temperature.
- Shipped in plastic tubes for protection of leads and to feed automatic placement equipment.
- Sensor package is infrared transparent and tinted to attenuate visible light.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)			
Parameter	Symbol	Rating	Units
Operating Temperature	T_{OPR}	-55 to +100	$^\circ\text{C}$
Storage Temperature	T_{STG}	-40 to +85	$^\circ\text{C}$
Soldering Temperature (Flow)	T_{SOL-F}		
Preheating Stage for 60 sec		183	$^\circ\text{C}$
Reflow Stage for 5 sec		230	$^\circ\text{C}$
Rate of Temperature Rise		3 to 10	$^\circ\text{C/S}$
EMITTER			
Continuous Forward Current	I_F	50	mA
Reverse Voltage	V_R	6	V
Power Dissipation ⁽¹⁾	P_D	100	mW
SENSOR			
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter-Collector Voltage	V_{ECO}	6	V
Collector Current	I_C	40	mA
Power Dissipation ⁽¹⁾	P_D	150	mW

NOTE:

1. Derate power dissipation linearly 1.33 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$.

PARAMETER	DEVICES	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
EMITTER							
Forward Voltage		$I_F = 20\text{ mA}$	V_F	—	—	1.4	V
Reverse Current		$V_R = 2\text{ V}$	I_R	—	—	100	μA
SENSOR							
Collector-Emitter Breakdown		$I_C = 1\text{ mA}, E_e = 0$	BV_{CEO}	30	—	—	V
Collector-Emitter Leakage		$V_{CE} = 5.25\text{ V}, E_e = 0$	I_{CEO}	—	—	30	μA
COUPLED							
On-State Collector Current	QCK3	$I_F = 5.0\text{ mA}, V_{CE} = 5\text{ V}$	$I_{C(ON)}$	1.0	—	—	mA
	QCK4			3.0		15.0	
Saturation Voltage		$I_F = 5\text{ mA}, I_C = 5.0\text{ mA}$	$V_{CE(SAT)}$	—	—	1.0	V

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.